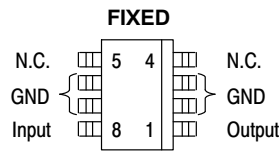
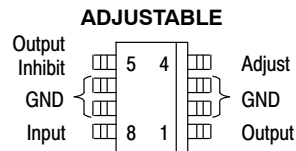


LM2931, NCV2931 Series

SOIC-8
D SUFFIX
CASE 751

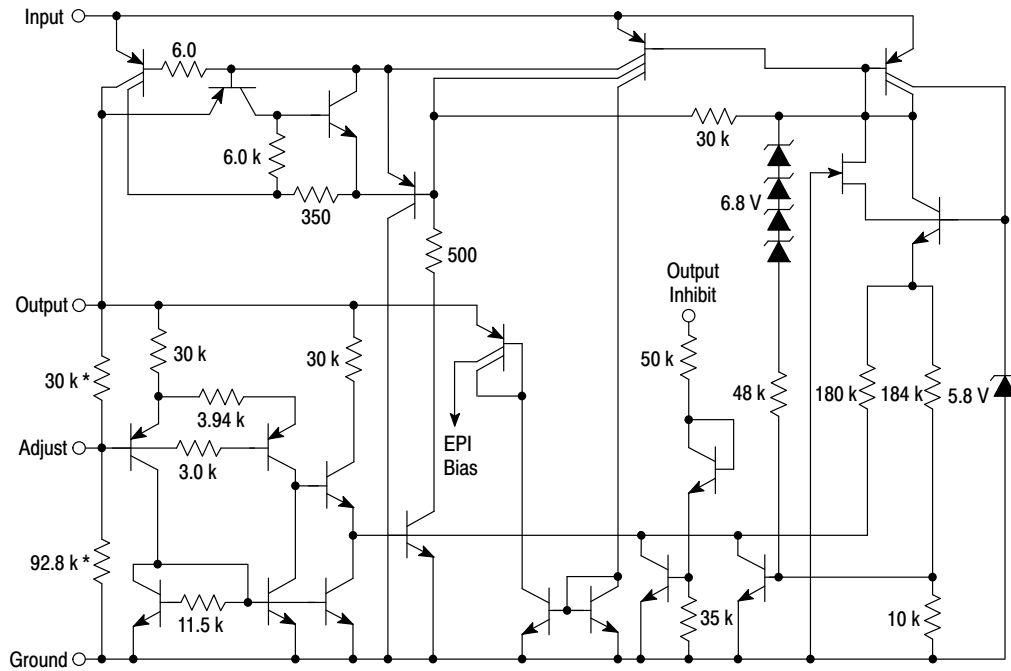


(Top View)



(Top View)

Representative Schematic Diagram



*Deleted on Adjustable Regulators

This device contains 26 active transistors.

LM2931, NCV2931 Series

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage Continuous	V_I	40	Vdc
Transient Input Voltage ($\tau \leq 100$ ms)	$V_I(\tau)$	60	Vpk
Transient Reverse Polarity Input Voltage 1.0% Duty Cycle, $\tau \leq 100$ ms	$-V_I(\tau)$	-50	Vpk
Electrostatic Discharge Sensitivity (ESD)			
Human Body Model (HBM) Class 2, JESD22 A114-C	–	2000	V
Machine Model (MM) Class A, JESD22 A115-A	–	200	V
Charged Device Model (CDM), JESD22 C101-C	–	2000	V
Power Dissipation			
Case 29 (TO-92 Type)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	178	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83	$^\circ\text{C/W}$
Case 221A, 314A, 314B and 314D (TO-220 Type)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	65	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	5.0	$^\circ\text{C/W}$
Case 318H (SOT-223)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	242	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	21	$^\circ\text{C/W}$
Case 369A (DPAK) (Note 1)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	92	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.0	$^\circ\text{C/W}$
Case 751 (SOP-8) (Note 2)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	160	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	25	$^\circ\text{C/W}$
Case 936 and 936A (D ² PAK) (Note 3)			
$T_A = 25^\circ\text{C}$	P_D	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	70	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	5.0	$^\circ\text{C/W}$
Operating Ambient Temperature Range	T_A	-40 to +125	$^\circ\text{C}$
Operating Die Junction Temperature	T_J	+150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. DPAK Junction-to-Ambient Thermal Resistance is for vertical mounting. Refer to Figure 25 for board mounted Thermal Resistance.
2. SOP-8 Junction-to-Ambient Thermal Resistance is for minimum recommended pad size. Refer to Figure 24 for Thermal Resistance variation versus pad size.
3. D²PAK Junction-to-Ambient Thermal Resistance is for vertical mounting. Refer to Figure 26 for board mounted Thermal Resistance.
4. NCV rated devices are subjected to and meet the AECQ-100 quality standards.

LM2931, NCV2931 Series

ELECTRICAL CHARACTERISTICS ($V_{in} = 14\text{ V}$, $I_O = 10\text{ mA}$, $C_O = 100\text{ }\mu\text{F}$, $C_{O(ESR)} = 0.3\text{ }\Omega$, $T_A = 25^\circ\text{C}$ [Note 5])

Characteristic	Symbol	LM2931–5.0/NCV2931–5.0			LM2931A–5.0/NCV2931A–5.0			Unit
		Min	Typ	Max	Min	Typ	Max	
FIXED OUTPUT								
Output Voltage	V _O							V
V _{in} = 14 V, I _O = 10 mA, T _A = 25°C		4.75	5.0	5.25	4.81	5.0	5.19	
V _{in} = 6.0 V to 26 V, I _O ≤ 100 mA, T _A = –40° to +125°C		4.50	–	5.50	4.75	–	5.25	
Line Regulation	Reg _{line}							mV
V _{in} = 9.0 V to 16 V		–	2.0	10	–	2.0	10	
V _{in} = 6.0 V to 26 V		–	4.0	30	–	4.0	30	
Load Regulation (I _O = 5.0 mA to 100 mA)	Reg _{load}	–	14	50	–	14	50	mV
Output Impedance	Z _O							mΩ
I _O = 10 mA, ΔI _O = 1.0 mA, f = 100 Hz to 10 kHz		–	200	–	–	200	–	
Bias Current	I _B							mA
V _{in} = 14 V, I _O = 100 mA, T _A = 25°C		–	5.8	30	–	5.8	30	
V _{in} = 6.0 V to 26 V, I _O = 10 mA, T _A = –40° to +125°C		–	0.4	1.0	–	0.4	1.0	
Output Noise Voltage (f = 10 Hz to 100 kHz)	V _n	–	700	–	–	700	–	μVrms
Long Term Stability	S	–	20	–	–	20	–	mV/kHR
Ripple Rejection (f = 120 Hz)	RR	60	90	–	60	90	–	dB
Dropout Voltage	V _I –V _O							V
I _O = 10 mA		–	0.015	0.2	–	0.015	0.2	
I _O = 100 mA		–	0.16	0.6	–	0.16	0.6	
Over–Voltage Shutdown Threshold	V _{th(OV)}	26	29.5	40	26	29.5	40	V
Output Voltage with Reverse Polarity Input (V _{in} = –15 V)	–V _O	–0.3	0	–	–0.3	0	–	V

5. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
6. NCV devices are qualified for automotive use.

LM2931, NCV2931 Series

ELECTRICAL CHARACTERISTICS ($V_{in} = 14\text{ V}$, $I_O = 10\text{ mA}$, $C_O = 100\text{ }\mu\text{F}$, $C_{O(ESR)} = 0.3\text{ }\Omega$, $T_A = 25^\circ\text{C}$ [Note 7])

Characteristic	Symbol	LM2931C/NCV2931C			LM2931AC/NCV2931AC			Unit
		Min	Typ	Max	Min	Typ	Max	
ADJUSTABLE OUTPUT								
Reference Voltage (Note 8, Figure 18) I _O = 10 mA, T _A = 25°C I _O ≤ 100 mA, T _A = −40 to +125°C	V _{ref}	1.14 1.08	1.20 –	1.26 1.32	1.17 1.15	1.20 –	1.23 1.25	V
Output Voltage Range	V _{O range}	3.0 to 24	2.7 to 29.5	–	3.0 to 24	2.7 to 29.5	–	V
Line Regulation (V _{in} = V _O + 0.6 V to 26 V)	Reg _{line}	–	0.2	1.5	–	0.2	1.5	mV/V
Load Regulation (I _O = 5.0 mA to 100 mA)	Reg _{load}	–	0.3	1.0	–	0.3	1.0	%/V
Output Impedance I _O = 10 mA, ΔI _O = 1.0 mA, f = 10 Hz to 10 kHz	Z _O	–	40	–	–	40	–	mΩ/V
Bias Current I _O = 100 mA I _O = 10 mA Output Inhibited (V _{th(OI)} = 2.5 V)	I _B	– – –	6.0 0.4 0.2	– 1.0 1.0	– – –	6.0 0.4 0.2	– 1.0 1.0	mA
Adjustment Pin Current	I _{Adj}	–	0.2	–	–	0.2	–	μA
Output Noise Voltage (f = 10 Hz to 100 kHz)	V _n	–	140	–	–	140	–	μVrms/V
Long-Term Stability	S	–	0.4	–	–	0.4	–	%/kHR
Ripple Rejection (f = 120 Hz)	RR	0.10	0.003	–	0.10	0.003	–	%/V
Dropout Voltage I _O = 10 mA I _O = 100 mA	V _I –V _O	– –	0.015 0.16	0.2 0.6	– –	0.015 0.16	0.2 0.6	V
Over-Voltage Shutdown Threshold	V _{th(OV)}	26	29.5	40	26	29.5	40	V
Output Voltage with Reverse Polarity Input (V _{in} = −15 V)	−V _O	−0.3	0	–	−0.3	0	–	V
Output Inhibit Threshold Voltages Output “On”: T _A = 25°C T _A = −40° to +125°C Output “Off”: T _A = 25°C T _A = −40° to +125°C	V _{th(OI)}	– – 2.50 3.25	2.15 – 2.26 –	1.90 1.20 – –	– – 2.50 3.25	2.15 – 2.26 –	1.90 1.20 – –	V
Output Inhibit Threshold Current (V _{th(OI)} = 2.5 V)	I _{th(OI)}	–	30	50	–	30	50	μA

7. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

8. The reference voltage on the adjustable device is measured from the output to the adjust pin across R_1 .

LM2931, NCV2931 Series

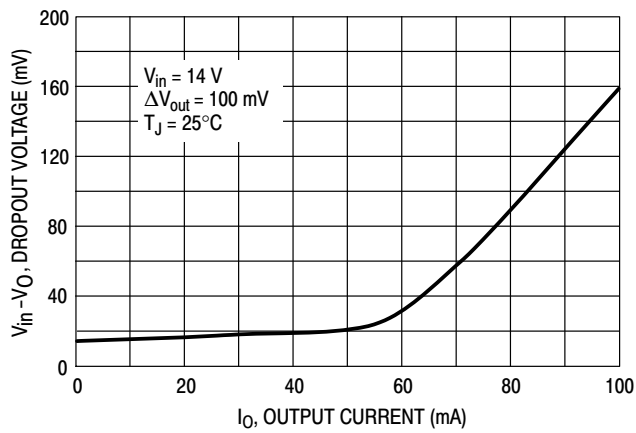


Figure 1. Dropout Voltage versus Output Current

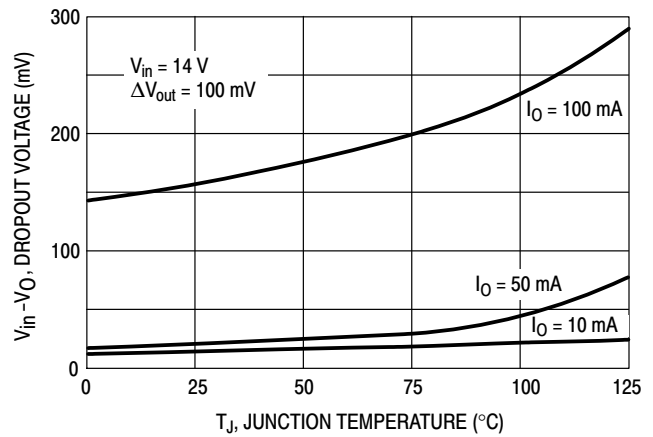


Figure 2. Dropout Voltage versus Junction Temperature

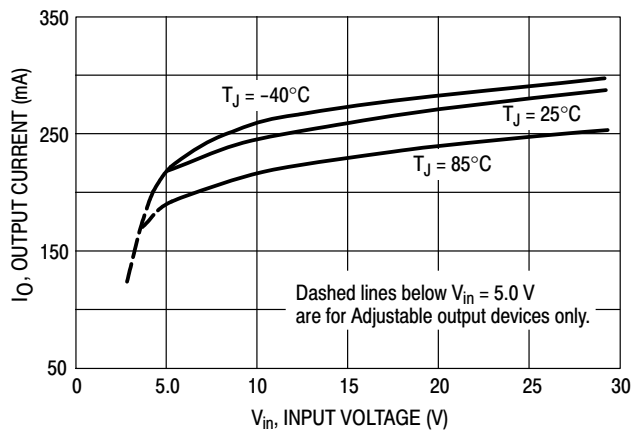


Figure 3. Peak Output Current versus Input Voltage

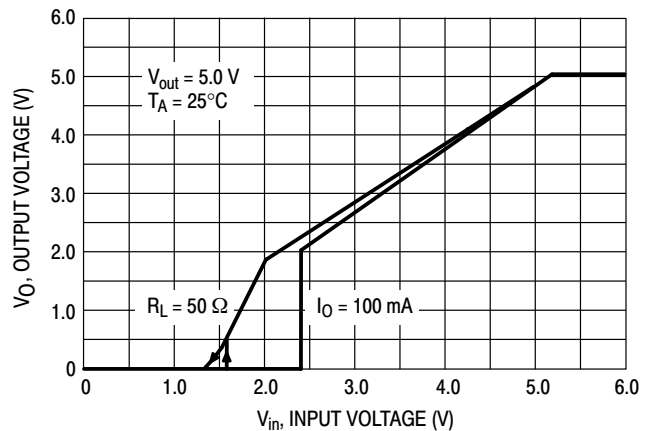


Figure 4. Output Voltage versus Input Voltage

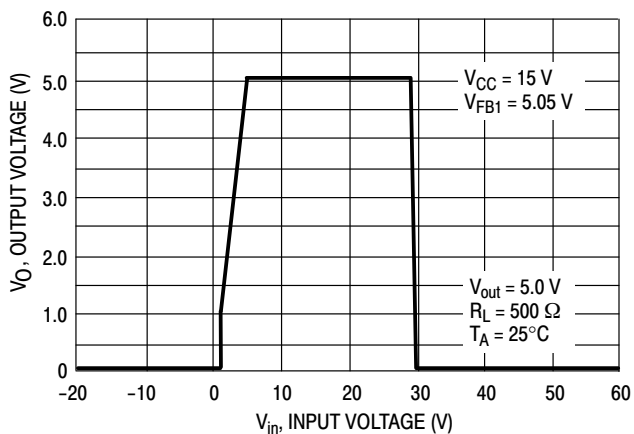


Figure 5. Output Voltage versus Input Voltage

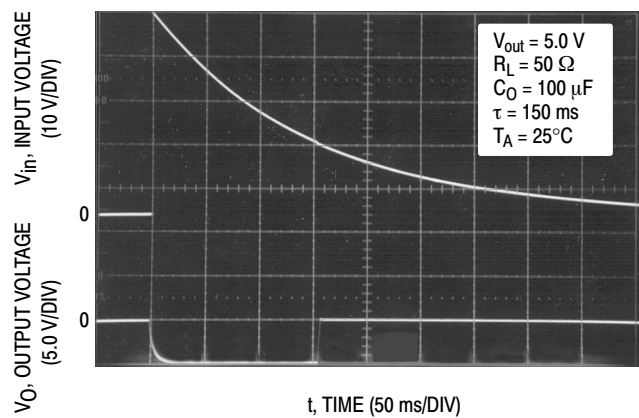


Figure 6. Load Dump Characteristics

LM2931, NCV2931 Series

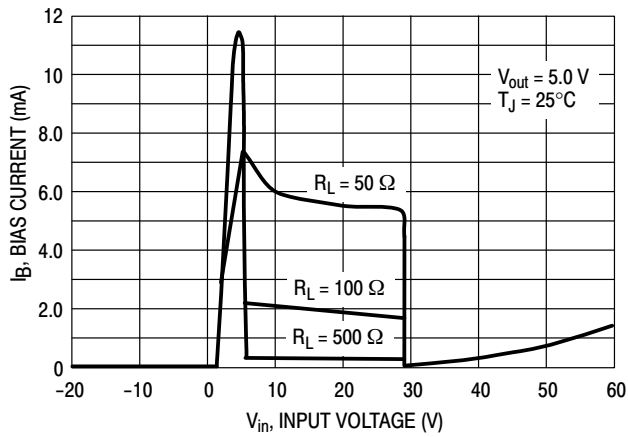


Figure 7. Bias Current versus Input Voltage

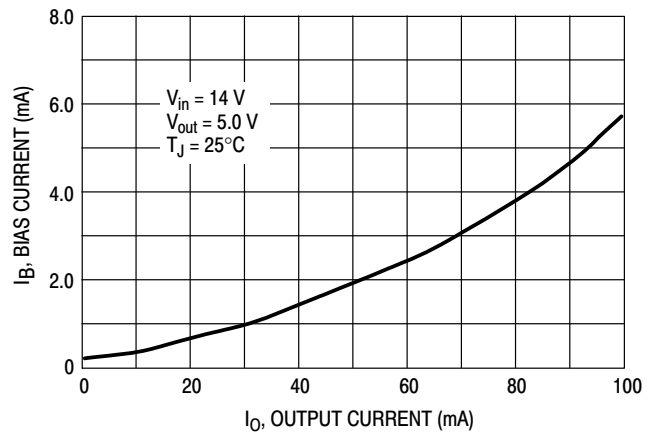


Figure 8. Bias Current versus Output Current

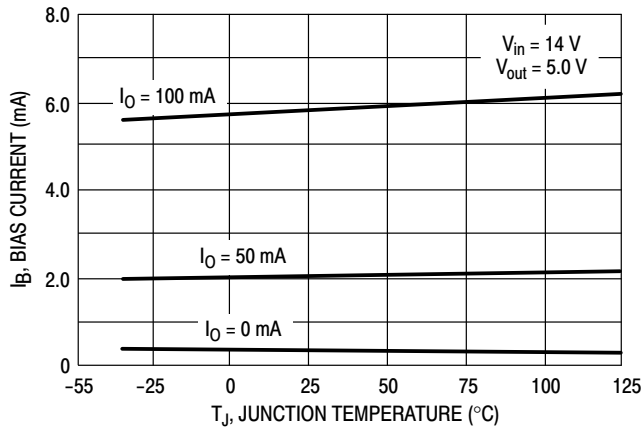


Figure 9. Bias Current versus Junction Temperature

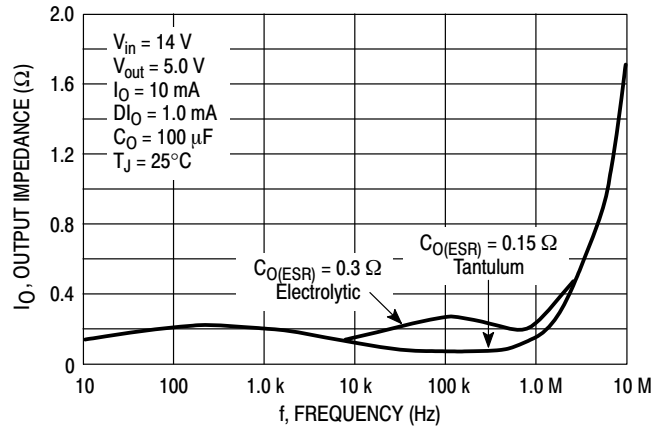


Figure 10. Output Impedance versus Frequency

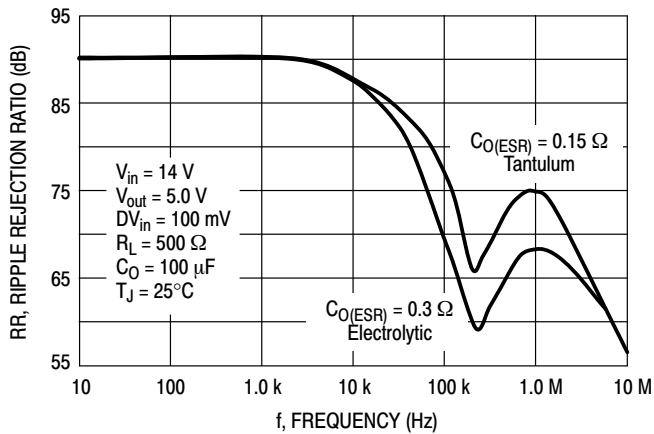


Figure 11. Ripple Rejection versus Frequency

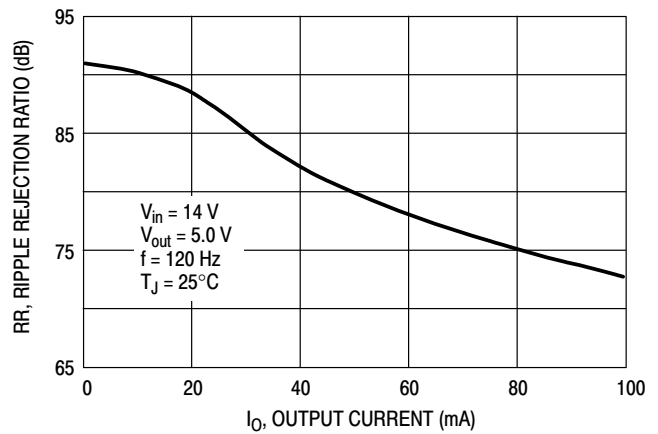


Figure 12. Ripple Rejection versus Output Current

LM2931, NCV2931 Series

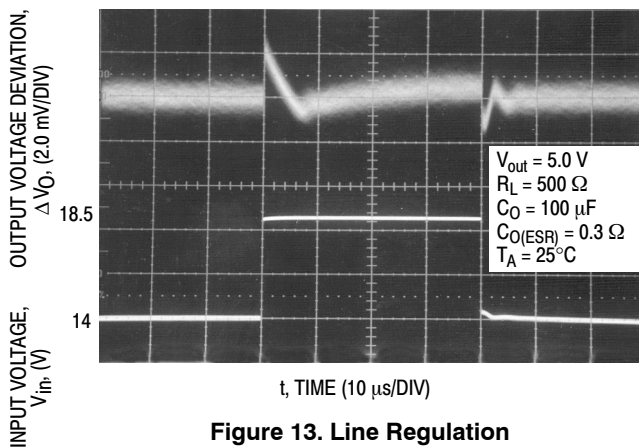


Figure 13. Line Regulation

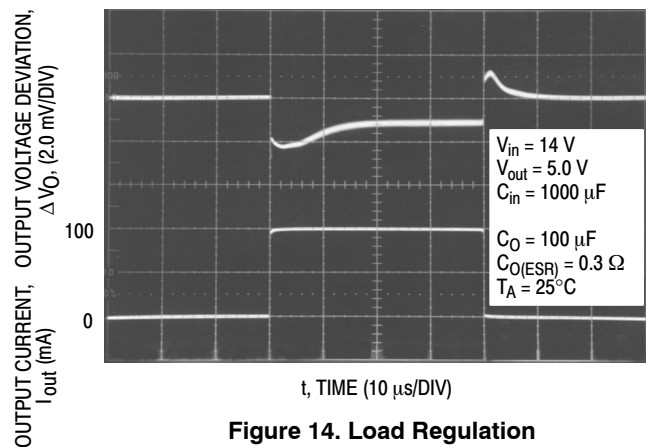


Figure 14. Load Regulation

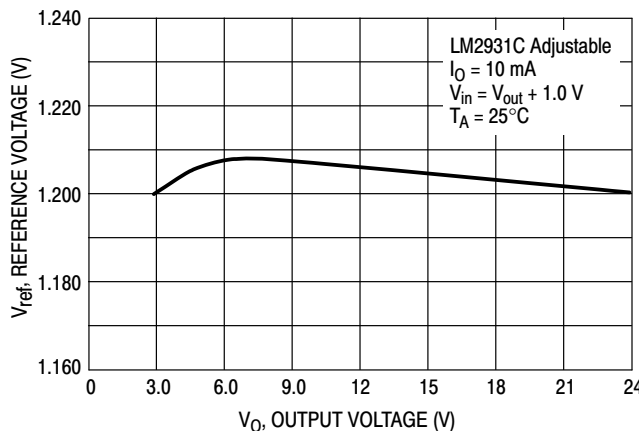


Figure 15. Reference Voltage versus Output Voltage

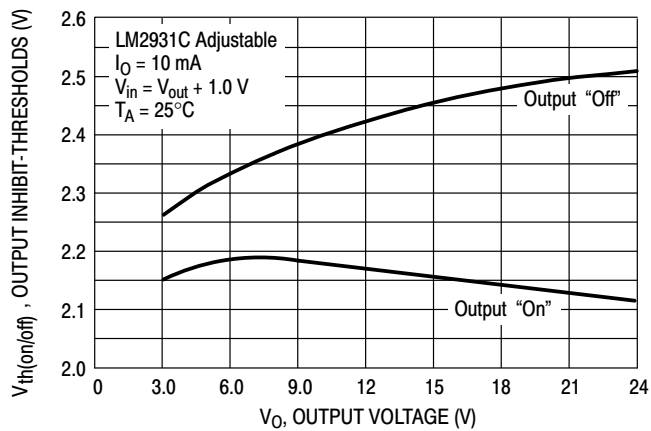


Figure 16. Output Inhibit-Thresholds versus Output Voltage

APPLICATIONS INFORMATION

The LM2931 series regulators are designed with many protection features making them essentially blow-out proof. These features include internal current limiting, thermal shutdown, overvoltage and reverse polarity input protection, and the capability to withstand temporary power-up with mirror-image insertion. Typical application circuits for the fixed and adjustable output device are shown in Figures 17 and 18.

The input bypass capacitor C_{in} is recommended if the regulator is located an appreciable distance ($\geq 4''$) from the supply input filter. This will reduce the circuit's sensitivity to the input line impedance at high frequencies.

This regulator series is not internally compensated and thus requires an external output capacitor for stability. The capacitance value required is dependent upon the load current, output voltage for the adjustable regulator, and the type of capacitor selected. The least stable condition is encountered at maximum load current and minimum output voltage. Figure 22 shows that for operation in the "Stable" region, under the conditions specified, the magnitude of the output capacitor impedance $|Z_O|$ must not exceed 0.4 Ω . This

limit must be observed over the entire operating temperature range of the regulator circuit.

With economical electrolytic capacitors, cold temperature operation can pose a serious stability problem. As the electrolyte freezes, around -30° C, the capacitance will decrease and the equivalent series resistance (ESR) will increase drastically, causing the circuit to oscillate. Quality electrolytic capacitors with extended temperature ranges of -40° to $+85^\circ$ C and -55° to $+105^\circ$ C are readily available. Solid tantalum capacitors may be a better choice if small size is a requirement, however, the maximum $|Z_O|$ limit over temperature must be observed.

Note that in the stable region, the output noise voltage is linearly proportional to $|Z_O|$. In effect, C_O dictates the high frequency roll-off point of the circuit. Operation in the area titled "Marginally Stable" will cause the output of the regulator to exhibit random bursts of oscillation that decay in an under-damped fashion. Continuous oscillation occurs when operating in the area titled "Unstable". It is suggested that oven testing of the entire circuit be performed with maximum load, minimum input voltage, and minimum ambient temperature.

LM2931, NCV2931 Series

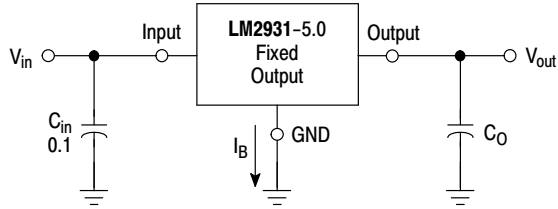
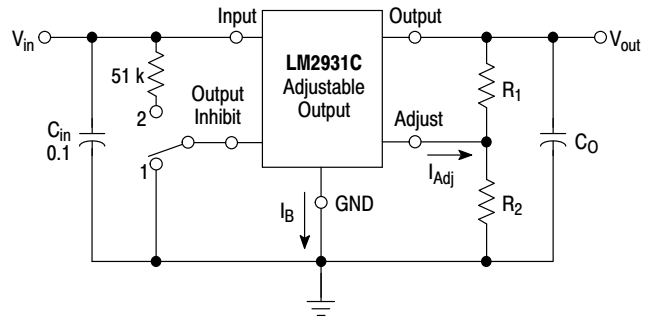


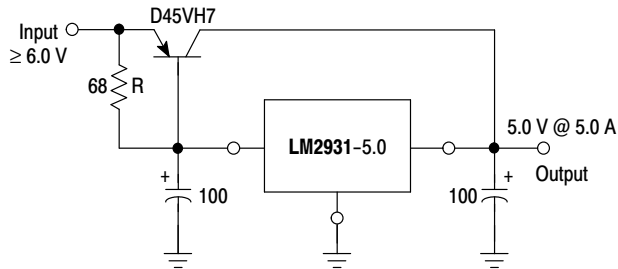
Figure 17. Fixed Output Regulator



Switch Position 1 = Output "On", 2 = Output "Off"

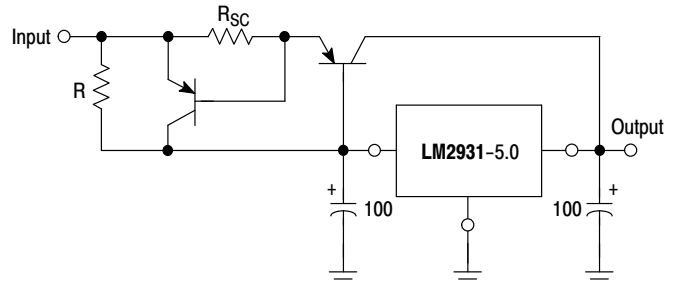
$$V_{out} = V_{ref} \left(1 + \frac{R_2}{R_1} \right) + I_{Adj} R_2 \quad 22.5 \text{ k} \geq \frac{R_1 R_2}{R_1 + R_2}$$

Figure 18. Adjustable Output Regulator



The LM2931 series can be current boosted with a PNP transistor. The D45VH7, on a heatsink, will provide an output current of 5.0 A with an input to output voltage differential of approximately 1.0 V. Resistor R in conjunction with the V_{BE} of the PNP determines when the pass transistor begins conducting. This circuit is not short circuit proof.

Figure 19. (5.0 A) Low Differential Voltage Regulator



The circuit of Figure 19 can be modified to provide supply protection against short circuits by adding the current sense resistor R_{SC} and an additional PNP transistor. The current sensing PNP must be capable of handling the short circuit current of the LM2931. Safe operating area of both transistors must be considered under worst case conditions.

Figure 20. Current Boost Regulator with Short Circuit Projection

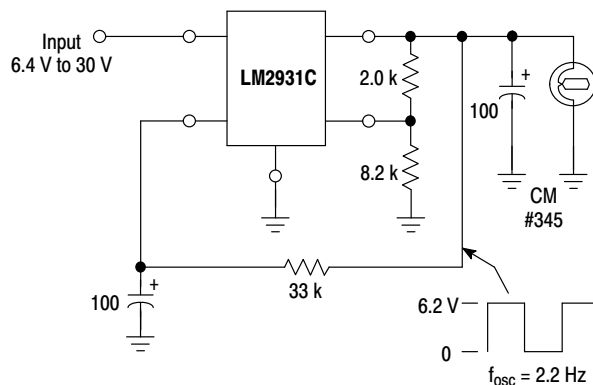


Figure 21. Constant Intensity Lamp Flasher

LM2931, NCV2931 Series

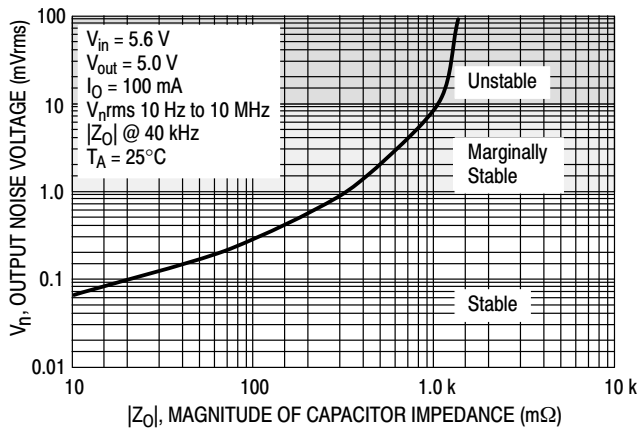


Figure 22. Output Noise Voltage vs. Output Capacitor Impedance

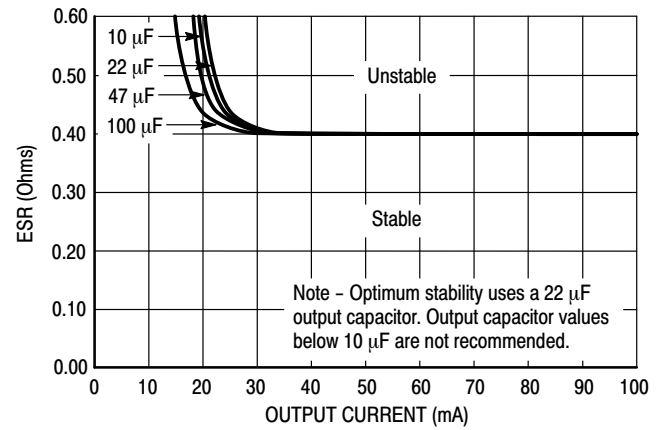


Figure 23. Output Capacitor ESR Stability vs. Output Load Current

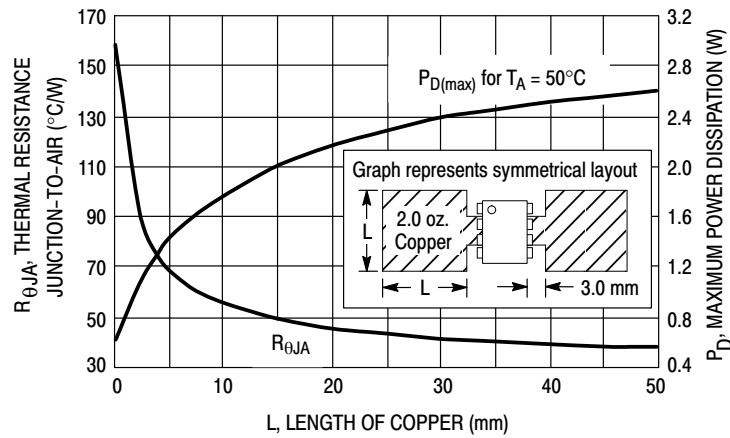


Figure 24. SOP-8 Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

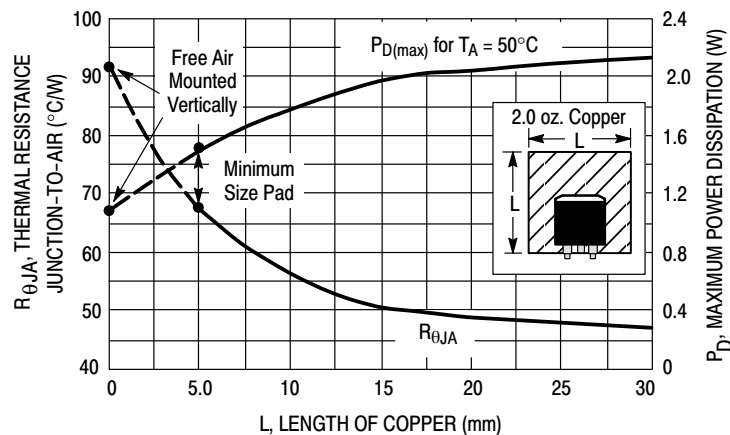


Figure 25. DPAK Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

LM2931, NCV2931 Series

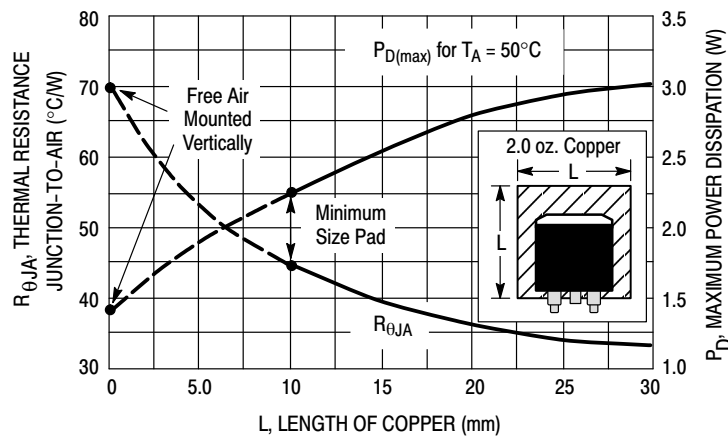


Figure 26. 3-Pin and 5-Pin D2PAK Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

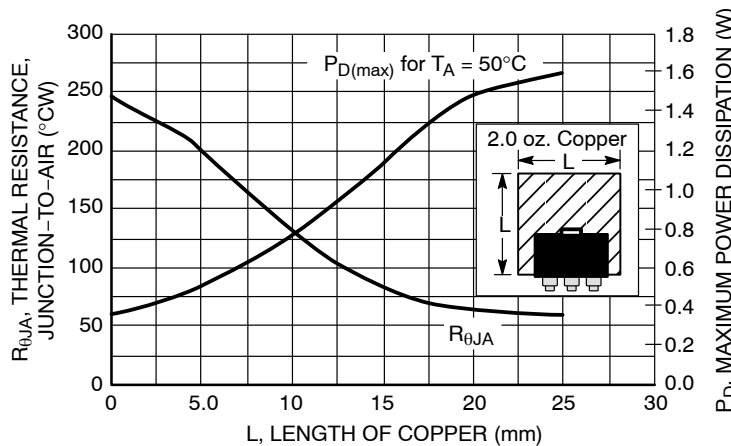


Figure 27. SOT-223 Thermal Resistance and Maximum Power Dissipation vs. P.C.B. Copper Length

DEFINITIONS

Dropout Voltage – The input/output voltage differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output decreases 100 mV from nominal value at 14 V input, dropout voltage is affected by junction temperature and load current.

Line Regulation – The change in output voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average chip temperature is not significantly affected.

Load Regulation – The change in output voltage for a change in load current at constant chip temperature.

Maximum Power Dissipation – The maximum total device dissipation for which the regulator will operate within specifications.

Bias Current – That part of the input current that is not delivered to the load.

Output Noise Voltage – The rms AC voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

Long-Term Stability – Output voltage stability under accelerated life test conditions with the maximum rated voltage listed in the devices electrical characteristics and maximum power dissipation.

LM2931, NCV2931 Series

ORDERING INFORMATION

Device	Output		Package	Shipping [†]
	Voltage	Tolerance		
LM2931AD-5.0	5.0 V	± 3.8%	SOIC-8	98 Units / Rail
LM2931AD-5.0G	5.0 V	± 3.8%	SOIC-8 (Pb-Free)	98 Units / Rail
LM2931AD-5.0R2	5.0 V	± 3.8%	SOIC-8	2500 / Tape & Reel
LM2931AD-5.0R2G	5.0 V	± 3.8%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM2931ADT-5.0	5.0 V	± 3.8%	DPAK	75 Units / Rail
LM2931ADT-5.0G	5.0 V	± 3.8%	DPAK (Pb-Free)	75 Units / Rail
LM2931ADT-5.0RK	5.0 V	± 3.8%	DPAK	2500 / VacPk Reel
LM2931ADT-5.0RKG	5.0 V	± 3.8%	DPAK (Pb-Free)	2500 / VacPk Reel
LM2931AD2T-5.0	5.0 V	± 3.8%	D ² PAK	50 Units / Rail
LM2931AD2T-5.0G	5.0 V	± 3.8%	D ² PAK (Pb-Free)	50 Units / Rail
LM2931AD2T-5.0R4	5.0 V	± 3.8%	D ² PAK	800 / VacPk Reel
LM2931AD2T-5.0R4G	5.0 V	± 3.8%	D ² PAK (Pb-Free)	800 / VacPk Reel
LM2931AT-5.0	5.0 V	± 3.8%	TO-220	50 Units / Rail
LM2931AT-5.0G	5.0 V	± 3.8%	TO-220 (Pb-Free)	50 Units / Rail
LM2931AZ-5.0	5.0 V	± 3.8%	TO-92	2000 / Inner Bag
LM2931AZ-5.0G	5.0 V	± 3.8%	TO-92 (Pb-Free)	2000 / Inner Bag
LM2931AZ-5.0RA	5.0 V	± 3.8%	TO-92	2000 / Tape & Reel
LM2931AZ-5.0RAG	5.0 V	± 3.8%	TO-92 (Pb-Free)	2000 / Tape & Reel
LM2931AZ-5.0RP	5.0 V	± 3.8%	TO-92	2000 / Ammo Pack
LM2931AZ-5.0RPG	5.0 V	± 3.8%	TO-92 (Pb-Free)	2000 / Ammo Pack
LM2931D-5.0	5.0 V	± 5.0%	SOIC-8	98 Units / Rail
LM2931D-5.0G	5.0 V	± 5.0%	SOIC-8 (Pb-Free)	98 Units / Rail
LM2931D-5.0R2	5.0 V	± 5.0%	SOIC-8	2500 / Tape & Reel
LM2931D-5.0R2G	5.0 V	± 5.0%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM2931D2T-5.0	5.0 V	± 5.0%	D ² PAK	50 Units / Rail
LM2931D2T-5.0G	5.0 V	± 5.0%	D ² PAK (Pb-Free)	50 Units / Rail
LM2931D2T-5.0R4	5.0 V	± 5.0%	D ² PAK	800 / VacPk Reel
LM2931D2T-5.0R4G	5.0 V	± 5.0%	D ² PAK (Pb-Free)	800 / VacPk Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV2931: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

LM2931, NCV2931 Series

ORDERING INFORMATION

Device	Output		Package	Shipping [†]
	Voltage	Tolerance		
LM2931DT-5.0	5.0 V	± 5.0%	DPAK	75 Units / Rail
LM2931DT-5.0G	5.0 V	± 5.0%	DPAK (Pb-Free)	75 Units / Rail
LM2931T-5.0	5.0 V	± 5.0%	TO-220	50 Units / Rail
LM2931T-5.0G	5.0 V	± 5.0%	TO-220 (Pb-Free)	50 Units / Rail
LM2931Z-5.0	5.0 V	± 5.0%	TO-92	2000 / Inner Bag
LM2931Z-5.0G	5.0 V	± 5.0%	TO-92 (Pb-Free)	2000 / Inner Bag
LM2931Z-5.0RA	5.0 V	± 5.0%	TO-92	2000 / Tape & Reel
LM2931Z-5.0RAG	5.0 V	± 5.0%	TO-92 (Pb-Free)	2000 / Tape & Reel
LM2931Z-5.0RP	5.0 V	± 5.0%	TO-92	2000 / Ammo Pack
LM2931Z-5.0RPG	5.0 V	± 5.0%	TO-92 (Pb-Free)	2000 / Ammo Pack
LM2931CD	Adjustable	± 5.0%	SOIC-8	98 Units / Rail
LM2931CDG	Adjustable	± 5.0%	SOIC-8 (Pb-Free)	98 Units / Rail
LM2931CDR2	Adjustable	± 5.0%	SOIC-8	2500 / Tape & Reel
LM2931CDR2G	Adjustable	± 5.0%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM2931CD2T	Adjustable	± 5.0%	D ² PAK	50 Units / Rail
LM2931CD2TG	Adjustable	± 5.0%	D ² PAK (Pb-Free)	50 Units / Rail
LM2931CD2TR4	Adjustable	± 5.0%	D ² PAK	800 / VacPk Reel
LM2931CD2TR4G	Adjustable	± 5.0%	D ² PAK (Pb-Free)	800 / VacPk Reel
LM2931CT	Adjustable	± 5.0%	TO-220	50 Units / Rail
LM2931CTG	Adjustable	± 5.0%	TO-220 (Pb-Free)	50 Units / Rail
LM2931ACD	Adjustable	± 2.0%	SOIC-8	98 Units / Rail
LM2931ACDG	Adjustable	± 2.0%	SOIC-8 (Pb-Free)	98 Units / Rail
LM2931ACDR2	Adjustable	± 2.0%	SOIC-8	2500 / Tape & Reel
LM2931ACDR2G	Adjustable	± 2.0%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM2931ACD2TR4	Adjustable	± 2.0%	D ² PAK	800 / VacPk Reel
LM2931ACD2TR4G	Adjustable	± 2.0%	D ² PAK (Pb-Free)	800 / VacPk Reel
LM2931ACTV	Adjustable	± 2.0%	TO-220	50 Units / Rail
LM2931ACTVG	Adjustable	± 2.0%	TO-220 (Pb-Free)	50 Units / Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV2931: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

LM2931, NCV2931 Series

ORDERING INFORMATION

Device	Output		Package	Shipping [†]
	Voltage	Tolerance		
NCV2931ACDR2*	Adjustable	± 2.5%	SOIC-8	2500 / Tape & Reel
NCV2931ACDR2G*	Adjustable	± 2.5%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NCV2931AD-5.0R2*	5.0 V	± 3.8%	SOIC-8	2500 / Tape & Reel
NCV2931AD-5.0R2G*	5.0 V	± 3.8%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NCV2931AST-5.0T3*	5.0 V	± 3.8%	SOT-223	4000 / Tape & Reel
NCV2931AST-5.0T3G*	5.0 V	± 3.8%	SOT-223 (Pb-Free)	4000 / Tape & Reel
NCV2931AZ-5.0G*	5.0 V	± 3.8%	TO-92 (Pb-Free)	2000 / Inner Bag
NCV2931AZ-5.0RAG*	5.0 V	± 3.8%	TO-92 (Pb-Free)	2000 / Tape & Reel
NCV2931CDR2*	Adjustable	± 5.0%	SOIC-8	2500 / Tape & Reel
NCV2931CDR2G*	Adjustable	± 5.0%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NCV2931D-5.0R2*	5.0 V	± 5.0%	SOIC-8	2500 / Tape & Reel
NCV2931D-5.0R2G*	5.0 V	± 5.0%	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NCV2931ADT-5.0RK*	5.0 V	± 3.8%	DPAK	2500 / Tape & Reel
NCV2931ADT5.0RKG*	5.0 V	± 3.8%	DPAK (Pb-Free)	2500 / Tape & Reel
NCV2931DT-5.0RK*	5.0 V	± 5.0%	DPAK	2500 / Tape & Reel
NCV2931DT-5.0RKG*	5.0 V	± 5.0%	DPAK (Pb-Free)	2500 / Tape & Reel
NCV2931ACD2TR4G*	Adjustable	± 2.5%	D ² PAK (Pb-Free)	800 / VacPk Reel
NCV2931D2T-5.0R4*	5.0 V	± 5.0%	D ² PAK	800 / VacPk Reel
NCV2931D2T5.0R4G*	5.0 V	± 5.0%	D ² PAK (Pb-Free)	800 / VacPk Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV2931: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

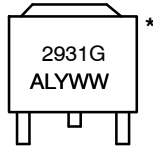
LM2931, NCV2931 Series

MARKING DIAGRAMS

**DPAK
DT SUFFIX
CASE 369A**



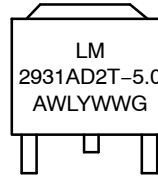
**DPAK
DT SUFFIX
CASE 369A**



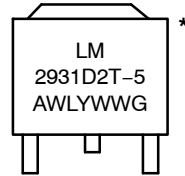
**D2PAK
D2T SUFFIX
CASE 936**



**D2PAK
D2T SUFFIX
CASE 936**

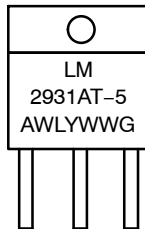


**D2PAK
D2T SUFFIX
CASE 936**

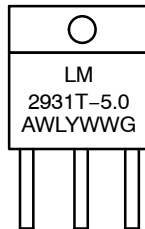


Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

**TO-220
T SUFFIX
CASE 221A**



**TO-220
T SUFFIX
CASE 221A**



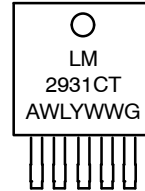
**TO-220
T SUFFIX
CASE 314D**



**D2PAK
D2T SUFFIX
CASE 936A**



**D2PAK
D2T SUFFIX
CASE 936A**

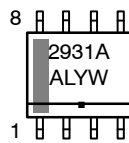


Heatsink surface connected to Pin 2.

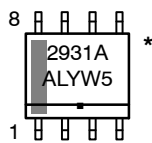
Heatsink surface connected to Pin 3.

Heatsink surface (shown as terminal 6 in case outline drawing) is connected to Pin 3.

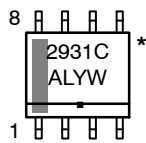
**SOIC-8
D SUFFIX
CASE 751**



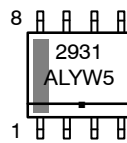
**SOIC-8
D SUFFIX
CASE 751**



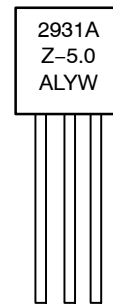
**SOIC-8
D SUFFIX
CASE 751**



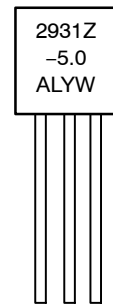
**SOIC-8
D SUFFIX
CASE 751**



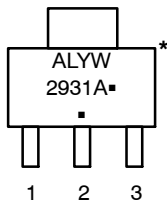
**TO-92
Z SUFFIX
CASE 029**



**TO-92
Z SUFFIX
CASE 029**



**SOT-223
ST SUFFIX
CASE 318H**



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Device

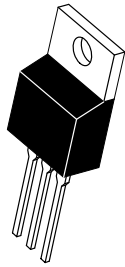
*This marking diagram also applies to NCV2931.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

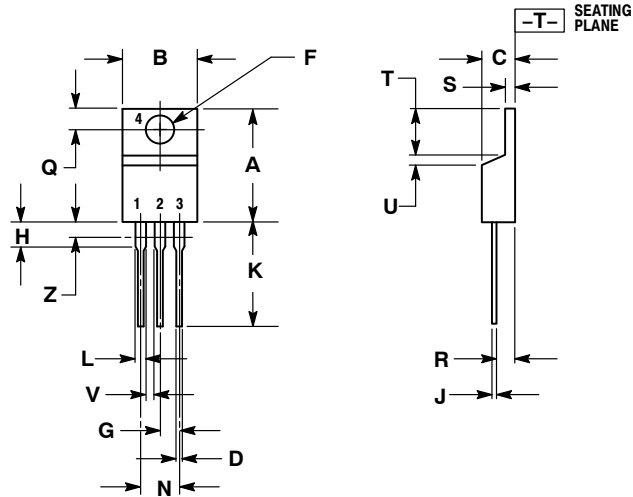
ON



SCALE 1:1

TO-220, SINGLE GAUGE CASE 221AB-01 ISSUE A

DATE 16 NOV 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.
4. PRODUCT SHIPPED PRIOR TO 2008 HAD DIMENSIONS
S = 0.045 - 0.055 INCHES (1.143 - 1.397 MM)

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.020	0.024	0.508	0.61
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 1:

- PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:

- PIN 1. BASE
2. EMITTER
3. COLLECTOR
4. EMITTER

STYLE 3:

- PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 4:

- PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2

STYLE 5:

- PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 6:

- PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 7:

- PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 8:

- PIN 1. CATHODE
2. ANODE
3. EXTERNAL TRIP/DELAY
4. ANODE

STYLE 9:

- PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 10:

- PIN 1. GATE
2. SOURCE
3. DRAIN
4. SOURCE

STYLE 11:


- PIN 1. DRAIN
2. SOURCE
3. GATE
4. SOURCE

DOCUMENT NUMBER: 98AON23085D

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DESCRIPTION: TO-220, SINGLE GAUGE

PAGE 1 OF 1

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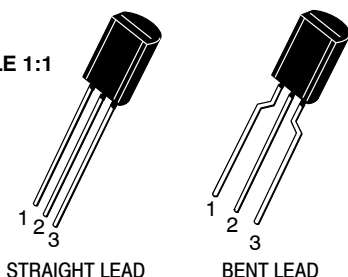
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1



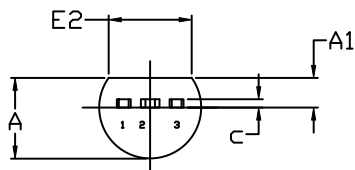
STRAIGHT LEAD

BENT LEAD

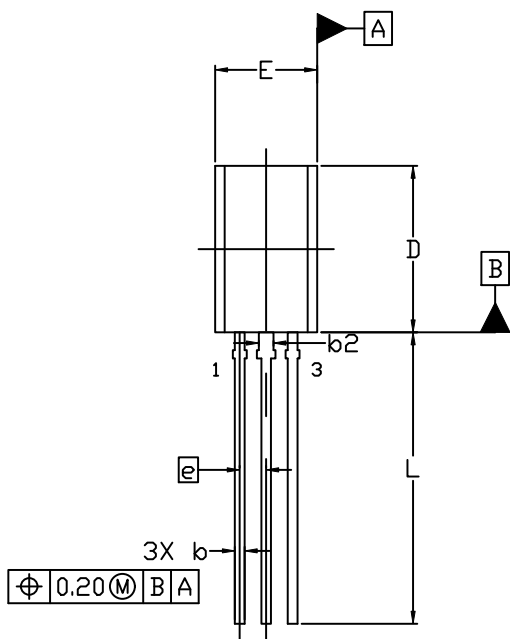
TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D

DATE 05 MAR 2021

STRAIGHT LEAD



END VIEW



TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	1.27 BSC		
L	13.80	14.00	14.20

STYLES AND MARKING ON PAGE 3

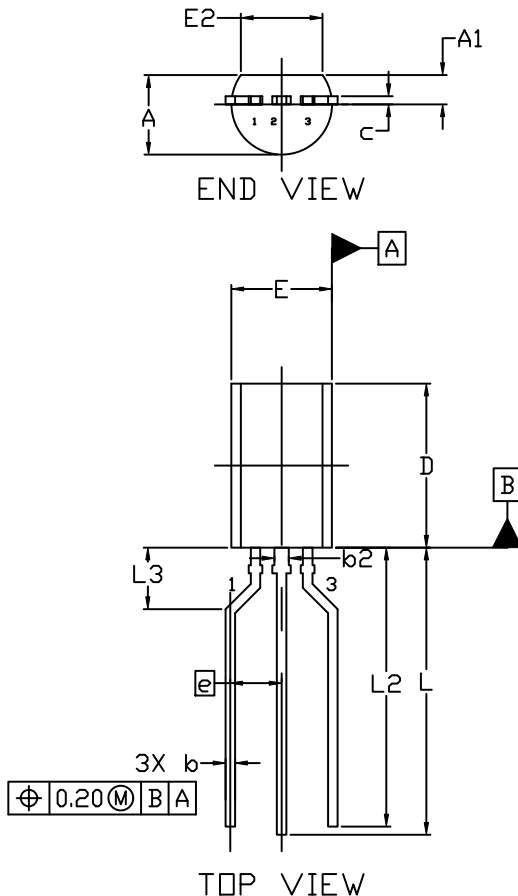
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TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D

DATE 05 MAR 2021

FORMED LEAD




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	2.50 BSC		
L	13.80	14.00	14.20
L2	13.20	13.60	14.00
L3	3.00 REF		

STYLES AND MARKING ON PAGE 3

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DESCRIPTION:	TO-92 (TO-226) 1 WATT	PAGE 2 OF 3

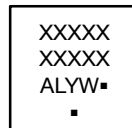
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TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D

DATE 05 MAR 2021

STYLE 1: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 2: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. DRAIN 2. SOURCE 3. GATE
STYLE 6: PIN 1. GATE 2. SOURCE & SUBSTRATE 3. DRAIN	STYLE 7: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 8: PIN 1. DRAIN 2. GATE 3. SOURCE & SUBSTRATE	STYLE 9: PIN 1. BASE 1 2. EMITTER 3. BASE 2	STYLE 10: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 11: PIN 1. ANODE 2. CATHODE & ANODE 3. CATHODE	STYLE 12: PIN 1. MAIN TERMINAL 1 2. GATE 3. MAIN TERMINAL 2	STYLE 13: PIN 1. ANODE 1 2. GATE 3. CATHODE 2	STYLE 14: PIN 1. EMITTER 2. COLLECTOR 3. BASE	STYLE 15: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2
STYLE 16: PIN 1. ANODE 2. GATE 3. CATHODE	STYLE 17: PIN 1. COLLECTOR 2. BASE 3. EMITTER	STYLE 18: PIN 1. ANODE 2. CATHODE 3. NOT CONNECTED	STYLE 19: PIN 1. GATE 2. ANODE 3. CATHODE	STYLE 20: PIN 1. NOT CONNECTED 2. CATHODE 3. ANODE
STYLE 21: PIN 1. COLLECTOR 2. EMITTER 3. BASE	STYLE 22: PIN 1. SOURCE 2. GATE 3. DRAIN	STYLE 23: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 24: PIN 1. EMITTER 2. COLLECTOR/ANODE 3. CATHODE	STYLE 25: PIN 1. MT 1 2. GATE 3. MT 2
STYLE 26: PIN 1. V _{CC} 2. GROUND 2 3. OUTPUT	STYLE 27: PIN 1. MT 2. SUBSTRATE 3. MT	STYLE 28: PIN 1. CATHODE 2. ANODE 3. GATE	STYLE 29: PIN 1. NOT CONNECTED 2. ANODE 3. CATHODE	STYLE 30: PIN 1. DRAIN 2. GATE 3. SOURCE
STYLE 31: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 32: PIN 1. BASE 2. COLLECTOR 3. EMITTER	STYLE 33: PIN 1. RETURN 2. INPUT 3. OUTPUT	STYLE 34: PIN 1. INPUT 2. GROUND 3. LOGIC	STYLE 35: PIN 1. GATE 2. COLLECTOR 3. EMITTER

**GENERIC
MARKING DIAGRAM***




XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

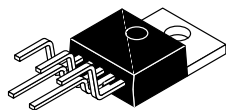
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TO-92 (TO-226) 1 WATT	PAGE 3 OF 3

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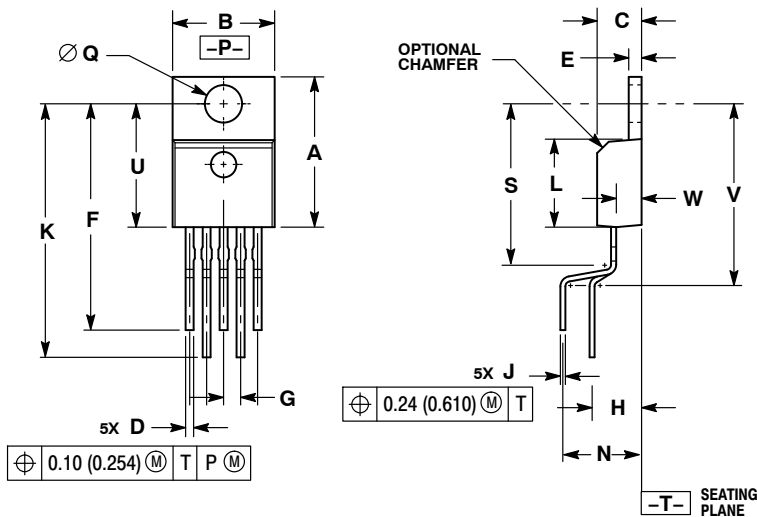
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

TO-220 5 LEAD OFFSET
CASE 314B-05
ISSUE L

DATE 01/07/1994



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.850	0.935	21.590	23.749
G	0.067 BSC		1.702 BSC	
H	0.166 BSC		4.216 BSC	
J	0.015	0.025	0.381	0.635
K	0.900	1.100	22.860	27.940
L	0.320	0.365	8.128	9.271
N	0.320 BSC		8.128 BSC	
Q	0.140	0.153	3.556	3.886
S	---	0.620	---	15.748
U	0.468	0.505	11.888	12.827
V	---	0.735	---	18.669
W	0.090	0.110	2.286	2.794

STYLE 1 THRU 4:
CANCELLED

STYLE 5:
PIN 1. GATE
2. MIRROR
3. DRAIN
4. KELVIN
5. SOURCE

DOCUMENT NUMBER:	98ASB42218B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TO-220 5 LEAD OFFSET	PAGE 1 OF 1

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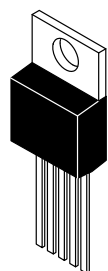
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

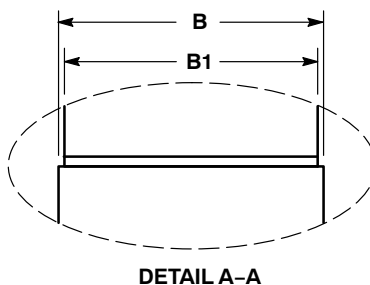
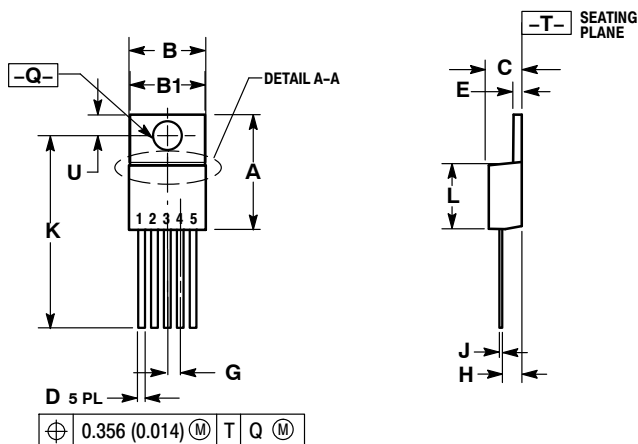


TO-220 5-LEAD CASE 314D-04 ISSUE H

DATE 29 JAN 2010



SCALE 1:1



NOTES:

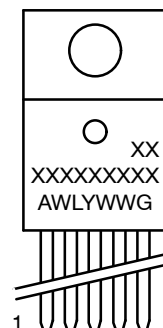
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
B1	0.375	0.415	9.525	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	0.977	1.045	24.810	26.543
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972

STYLE 1 THRU 4:

1. OBSOLETE

GENERIC MARKING DIAGRAM*

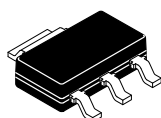


A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	TO-220 5-LEAD	PAGE 1 OF 1

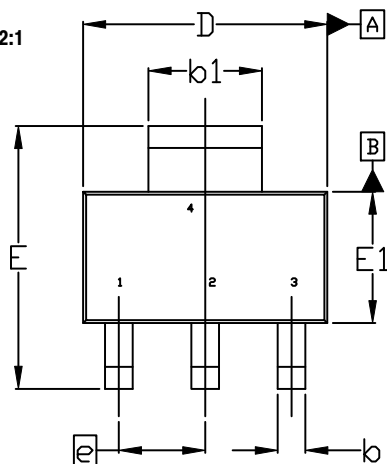
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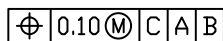
SOT-223 CASE 318H ISSUE B

DATE 13 MAY 2020

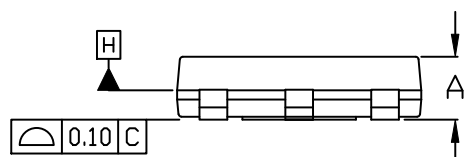
SCALE 2:1



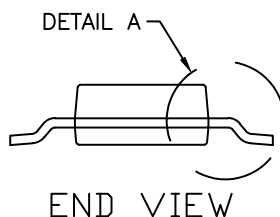
TOP VIEW



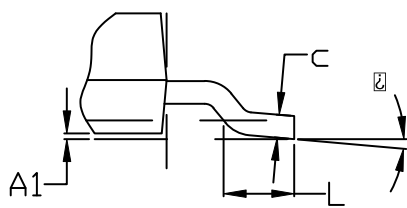
NOTE 7



SIDE VIEW

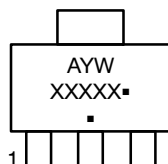


END VIEW



DETAIL A

GENERIC MARKING DIAGRAM*



A = Assembly Location
Y = Year
W = Work Week
XXXXX = Specific Device Code
▪ = Pb-Free Package

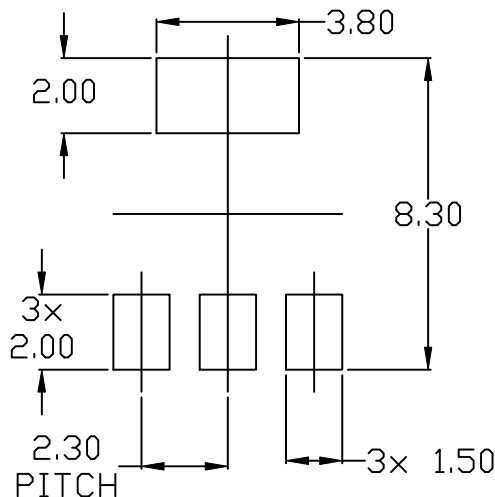
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E1 ARE DETERMINED AT DATUM H. DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. SHALL NOT EXCEED 0.23mm PER SIDE.
4. LEAD DIMENSIONS b AND b1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS 0.08mm PER SIDE.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
7. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS b AND b1.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.80
A1	0.02	0.06	0.11
b	0.60	0.74	0.88
b1	2.90	3.00	3.10
c	0.24	---	0.35
D	6.30	6.50	6.70
E	6.70	7.00	7.30
E1	3.30	3.50	3.70
e	2.30 BSC		
L	0.25	---	---
⌀	0°	---	10°



RECOMMENDED MOUNTING FOOTPRINT

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

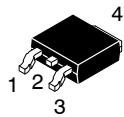
DOCUMENT NUMBER:	98ASH70634A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOT-223	PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

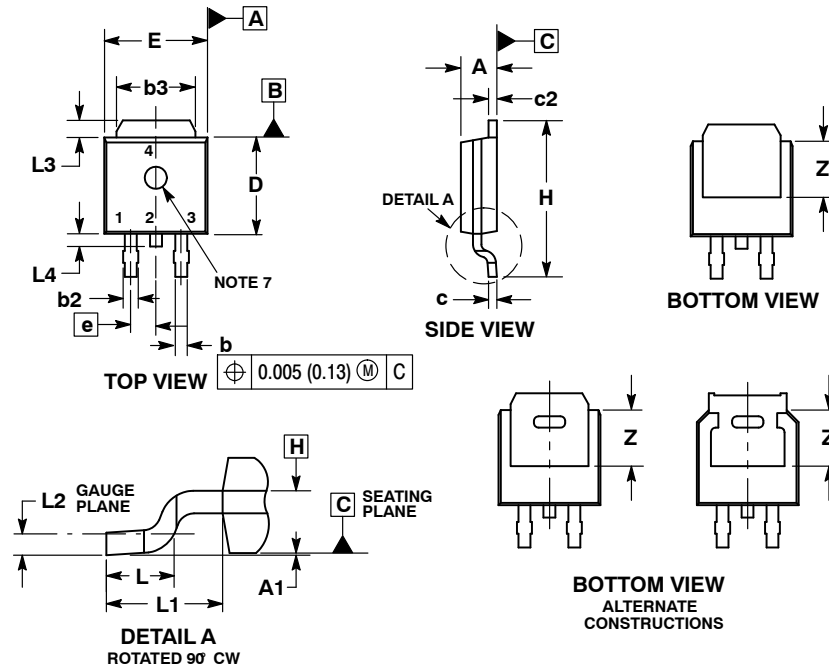
ON



SCALE 1:1

DPAK (SINGLE GAUGE) CASE 369C ISSUE F

DATE 21 JUL 2015

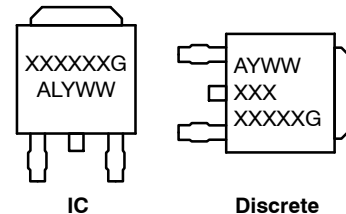


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

GENERIC MARKING DIAGRAM*

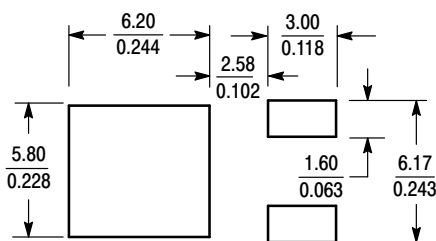


XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

- STYLE 1:**
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR
- STYLE 2:**
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN
- STYLE 3:**
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE
- STYLE 4:**
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE
- STYLE 5:**
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE
- STYLE 6:**
PIN 1. MT1
2. MT2
3. GATE
4. MT2
- STYLE 7:**
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR
- STYLE 8:**
PIN 1. N/C
2. CATHODE
3. ANODE
4. CATHODE
- STYLE 9:**
PIN 1. ANODE
2. CATHODE
3. RESISTOR ADJUST
4. CATHODE
- STYLE 10:**
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

SOLDERING FOOTPRINT*



SCALE 3:1 (mm inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DPAK (SINGLE GAUGE)	PAGE 1 OF 1

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

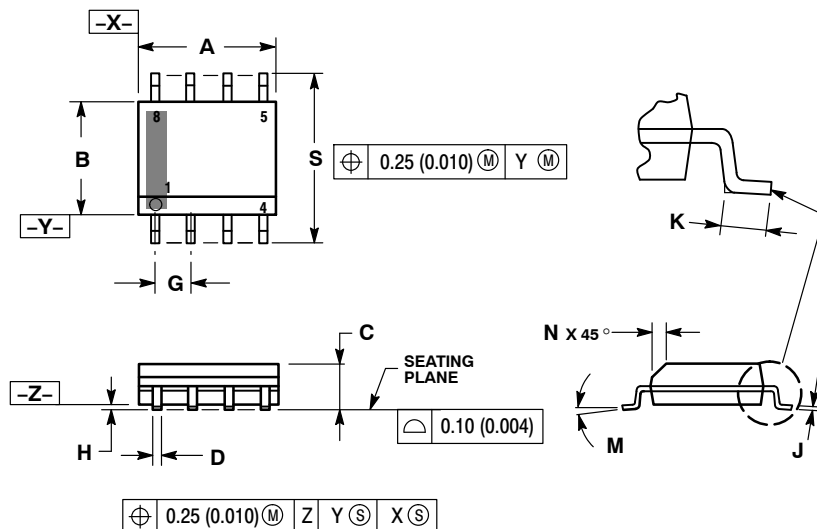
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SCALE 1:1

SOIC-8 NB
CASE 751-07
ISSUE AK

DATE 16 FEB 2011

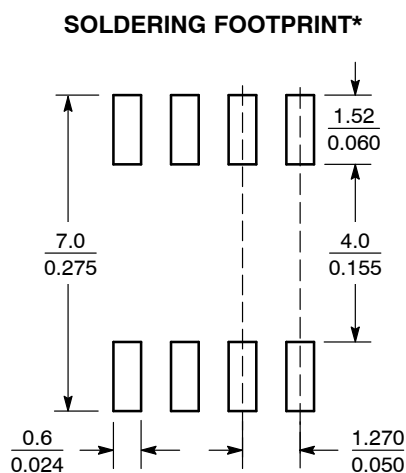


NOTES:

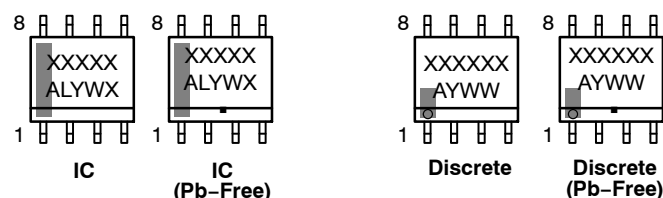
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

GENERIC MARKING DIAGRAM*



SCALE 6:1 (mm/inches)



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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SOIC-8 NB
CASE 751-07
ISSUE AK

DATE 16 FEB 2011

STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1	STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1	STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE
STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1
STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE	STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1	STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6	STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND	STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT	STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE
STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC	STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

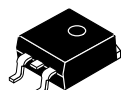
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DESCRIPTION:	SOIC-8 NB	PAGE 2 OF 2

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

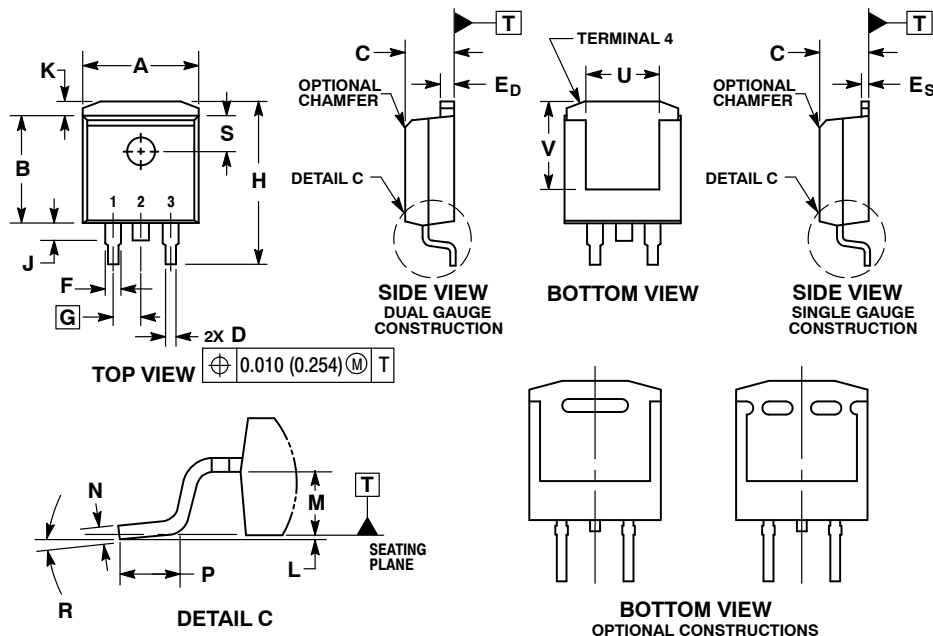
ON Semiconductor®



SCALE 1:1

D²PAK
CASE 936-03
ISSUE E

DATE 29 SEP 2015

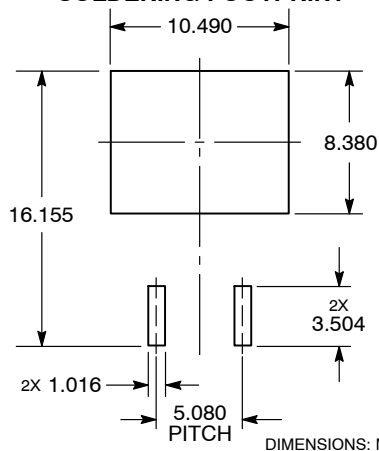


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCHES.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.
6. SINGLE GAUGE DESIGN WILL BE SHIPPED AFTER FPCN EXPIRATION IN OCTOBER 2011.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E _D	0.045	0.055	1.143	1.397
E _S	0.018	0.026	0.457	0.660
F	0.051 REF		1.295 REF	
G	0.100 BSC		2.540 BSC	
H	0.539	0.579	13.691	14.707
J	0.125 MAX		3.175 MAX	
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	0°	8°	0°	8°
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

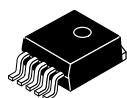
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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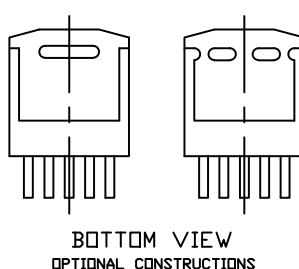
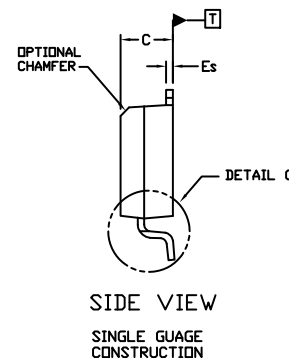
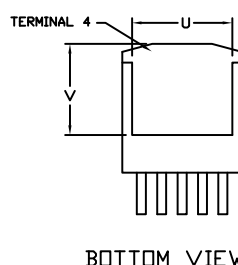
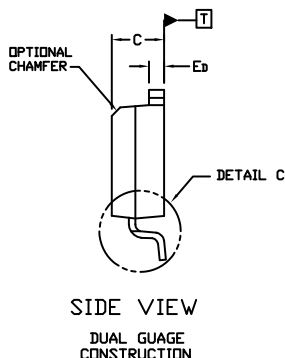
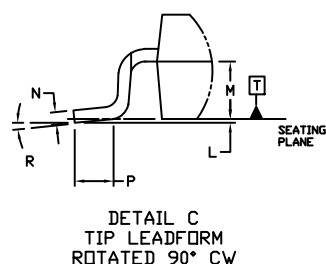
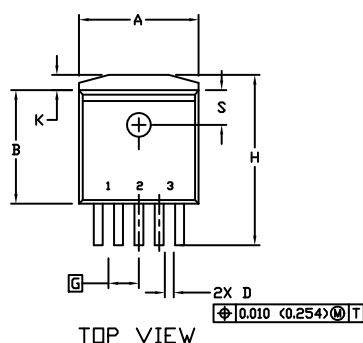
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DATE 28 JUL 2021

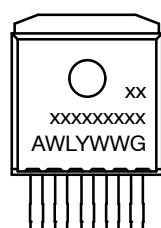
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NOTES:

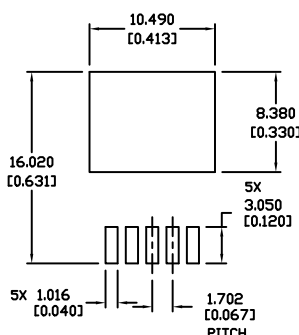
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCHES
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

GENERIC MARKING DIAGRAM*



xxxxxx = Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.396	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
Ed	0.045	0.055	1.143	1.397
Es	0.018	0.026	0.457	0.660
G	0.067	BSC	1.702	BSC
H	0.539	0.579	13.691	14.707
K	0.050	REF	1.270	REF
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	0°	8°	0°	8°
S	0.116	REF	2.946	REF
U	0.200	MIN	5.080	MIN
V	0.250	MIN	6.350	MIN

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